

CGHV22300MP

300 W, 1800 -2200 MHz, GaN HEMT for LTE

Cree's CGHV22300MP is a gallium nitride (GaN) high electron mobility transistor (HEMT) is designed specifically for high efficiency, high gain and wide bandwidth capabilities, which makes the CGHV22300MP ideal for 1.8 -2.2 GHz LTE and BWA amplifier applications. The transistor is input matched and supplied in an overmold package.



PN: CGHV22300MP

Typical Performance Over 2.11 - 2.17 GHz ($T_c = 25$ °c) of Demonstration Amplifier

Parameter	2.11 GHz	2.14 GHz	2.17 GHz	Units
Gain @ 47.8 dBm	17.0	17.2	17.6	dB
ACLR @ 47.8 dBm	-35.0	-34.5	-33.0	dBc
Drain Efficiency @ 47.8 dBm	31.1	31.5	32.1	%

Note:

Measured in the CGHV22300MP-TB amplifier circuit, under WCDMA 3GPP test model 1, 64 DPCH, 45% clipping, $PAR = 7.5 \text{ dB} \oplus 0.01\%$ Probability on CCDF.

Features

- 1.8 2.2 GHz Operation
- 17 dB Gain
- 60 W Average Output Power
- -35 dBc ACLR at 60 W P_{AVE}
- 32% Efficiency at 60 W P_{AVE}
- High Degree of DPD Correction Can be Applied





Absolute Maximum Ratings (not simultaneous)

Parameter	Symbol	Rating	Units	Units
Drain-Source Voltage	$V_{\scriptscriptstyle DSS}$	125	Volts	25°C
Gate-to-Source Voltage	V_{GS}	-10, +2	Volts	25°C
Storage Temperature	T _{STG}	-65, +150	°C	
Operating Junction Temperature	T ₃	225	°C	
Maximum Forward Gate Current	I_{GMAX}	42	mA	25°C
Maximum Drain Current ¹	I _{DMAX}	15.6	Α	25°C
Soldering Temperature ²	T _s	245	°C	
Thermal Resistance, Junction to Case ³	$R_{_{ heta JC}}$	1.03	°C/W	85° C, $P_{DISS} = 125 \text{ W}$
Case Operating Temperature ⁴	T _c	-40, +150	°C	30 seconds

Note:

- ¹ Current limit for long term, reliable operation.
- ² Refer to the Application Note on soldering at http://www.cree.com/rf/document-library
- ³ Measured for the CGHV22300MP
- ⁴ See also, the Power Dissipation De-rating Curve on Page 4

Electrical Characteristics ($T_c = 25$ °C)

Characteristics	Symbol	Min.	Тур.	Max.	Units	Conditions
DC Characteristics¹						
Gate Threshold Voltage	$V_{GS(th)}$	-3.8	-3.0	-2.3	V _{DC}	$V_{DS} = 10 \text{ V, I}_{D} = 42 \text{ mA}$
Gate Quiescent Voltage	$V_{GS(Q)}$	-	-2.7	-	V _{DC}	$V_{DS} = 50 \text{ V}, I_{D} = 1.0 \text{ A}$
Saturated Drain Current ²	I _{DS}	31.2	37.4	-	Α	$V_{DS} = 6.0 \text{ V}, V_{GS} = 2.0 \text{ V}$
Drain-Source Breakdown Voltage	$V_{\rm BR}$	125	-	-	V _{DC}	$V_{GS} = -8 \text{ V, } I_{D} = 42 \text{ mA}$
RF Characteristics ⁵ (T _c = 25 °C, F ₀	= 2.14 GHz ı	ınless other	wise noted)			
Saturated Output Power ^{3,4}	P _{SAT}	-	300	-	W	$V_{DD} = 50 \text{ V}, I_{DQ} = 1.0 \text{ A}$
Pulsed Drain Efficiency ³	η	-	70	-	%	$V_{DD} = 50 \text{ V}, I_{DQ} = 1.0 \text{ A}, P_{OUT} = P_{SAT}$
Gain ⁶	G	-	17	-	dB	$V_{DD} = 50 \text{ V, } I_{DQ} = 1.0 \text{ A, } P_{OUT} = 47.8 \text{ dBm}$
WCDMA Linearity ⁶	ACLR	-	-35	-	dBc	$V_{\scriptscriptstyle DD}$ = 50 V, $I_{\scriptscriptstyle DQ}$ = 1.0 A, $P_{\scriptscriptstyle OUT}$ = 47.8 dBm
Drain Efficiency ⁶	η	-	32	-	%	$V_{\scriptscriptstyle DD}$ = 50 V, $I_{\scriptscriptstyle DQ}$ = 1.0 A, $P_{\scriptscriptstyle OUT}$ = 47.8 dBm
Output Mismatch Stress ³	VSWR	-	-	10 : 1	Ψ	No damage at all phase angles, V_{DD} = 50 V, I_{DQ} = 1.0 A, P_{OUT} = 200 W Pulsed
Dynamic Characteristics						
Input Capacitance ⁷	C _{GS}	-	-	-	pF	$V_{DS} = 50 \text{ V}, V_{gs} = -8 \text{ V}, f = 1 \text{ MHz}$
Output Capacitance ⁷	C _{DS}	-	-	-	pF	$V_{DS} = 50 \text{ V, } V_{gs} = -8 \text{ V, } f = 1 \text{ MHz}$
Feedback Capacitance	C_{GD}	-	-	-	pF	$V_{DS} = 50 \text{ V, } V_{gs} = -8 \text{ V, } f = 1 \text{ MHz}$

Notes:

- $^{\scriptscriptstyle 1}$ Measured on wafer prior to packaging.
- ² Scaled from PCM data.
- 3 Pulse Width = 100 μ S, Duty Cycle = 10%
- $^{\rm 4}$ $\rm P_{SAT}$ is defined as $\rm I_{\rm G}$ = 4 mA peak.
- ⁵ Measured in CGHV22300MP-TB.
- ⁶ Single Carrier WCDMA, 3GPP Test Model 1, 64 DPCH, 45% Clipping, PAR = 7.5 dB @ 0.01% Probability on CCDF.
- $^{\rm 7}$ Includes package and internal matching components.



Typical Performance

Figure 1. - Small Signal S-Parameters $V_{DD} = 50 \text{ V}, I_{DQ} = 1.0 \text{ A}$

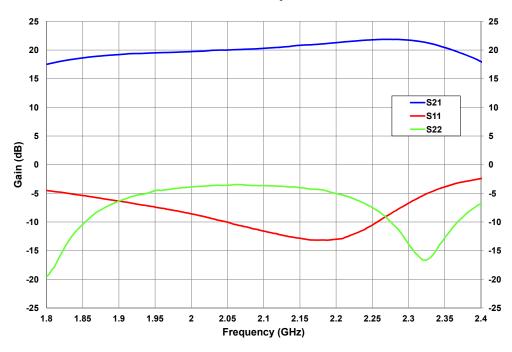
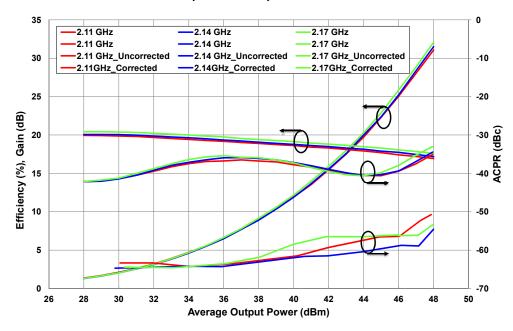


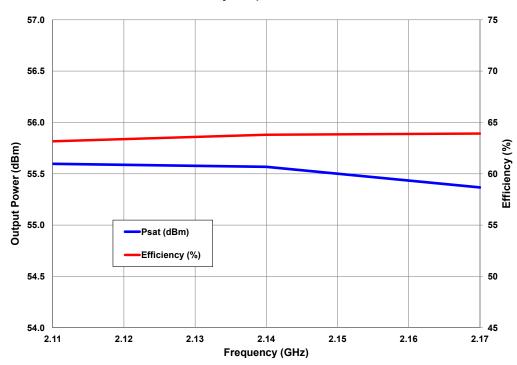
Figure 2. - Typical Gain, Drain Efficiency and ACPR vs Average Output Power $P_{\text{OUT}} = 60 \text{ W Avg}, \text{W-CDMA}, 5 \text{ MHz}, \text{Single Carrier},$ Test Model 1, 64 DPCH, 7.5 dB @ 0.01%

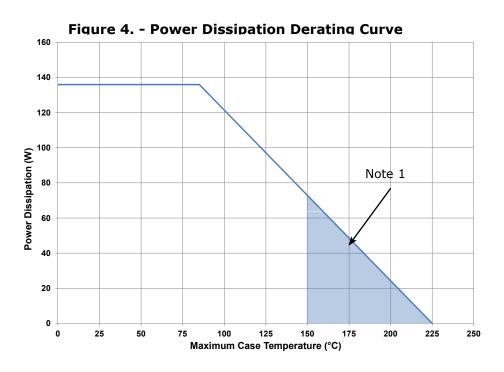




Typical Performance

Figure 3. - Typical Saturated Output Power and Efficiency vs Frequency 100 μ sec, 10%

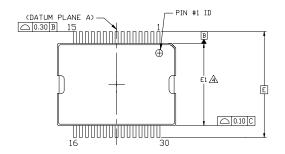




Note 1. Area exceeds Maximum Case Operating Temperature (See Page 2).



Product Dimensions CGHV22300MP (Package Type)

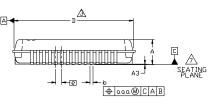


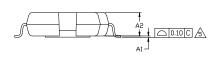
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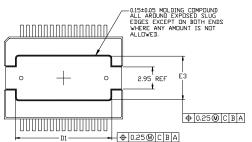
- 1. DIMENSIONING & TOLERANCES PER ANSI,Y14.5M-1994.
- A DIMENSION 'D' DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS, MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

 A DIMENSION 'E1' DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. SHALL NOT EXCEED 0.15 PER SIDE.

 A COMMENT OF THE STATE O
- FIRMED LEADS SHALL BE PLANAR WITH RESPECT TO DIE ANOTHER WITHIN 0.076mm AT SEATING PLANE.
- 6. CONTROLLING DIMENSION: MILLIMETERS.
- \triangle SEATING PLANE IS DEFINED BY LEAD TIPS ONLY.







				IN	
SYMBOL	COMMON DIMENSIONS				
STRIBUL	MIN.	NDM.	MAX.		
Α		_	3.60		
A1	0.10	0.20	0.30		
A2	3.00	3.15	3,30		
A3	0	0.05	0.10		
aaa		0.20			
م	0.35		0.48		
D	1	5.90 BSC		3	
D1	9.00		13.00		
E	1	4.20 BS0			
E1		11.00 BSC		4	
E3	5.80		6.20		
_		120 BCC			

	FUNCTION
1	NC NC
2	NC
3	NC I
4	RF INPUT
5	RF INPUT
6	RF INPUT
7	RF INPUT
8	RF INPUT
9	RF INPUT
10	RF INPUT
11 12 13 14 15 16 17	RF INPUT
12	RF INPUT NC
13	NC
14	NC
15	NC VIDEO BIAS FEED
16	VIDEO BIAS FEED VIDEO BIAS FEED
17	
18	NC
18 19 20	RF DUTPUT
20	RF DUTPUT
21 22 23 24	RF OUTPUT
22	RF DUTPUT
23	RF DUTPUT
24	RF DUTPUT
20 21 22 23 24 25 26	RF DUTPUT
26 27	RF DUTPUT
27 28 29	RF DUTPUT
28	NC
29	VIDEO BIAS FEED
30	VIDEO BIAS FEED

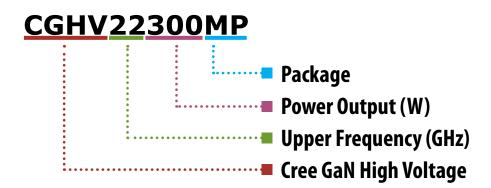
PINOUT TABLE

Pin	Input/Output
1	NC
2	NC
3	NC
4	RF IN
5	RF IN
6	RF IN
7	RF IN
8	RF IN
9	RF IN
10	RF IN
11	RF IN
12	RF IN
13	NC
14	NC
15	NC

Pin	Input/Output	
16	VIDEO BIAS FEED	
17	VIDEO BIAS FEED	
18	NC	
19	RF OUT	
20	RF OUT	
21	RF OUT	
22	RF OUT	
23	RF OUT	
24	RF OUT	
25	RF OUT	
26	RF OUT	
27	RF OUT	
28	NC	
29	VIDEO BIAS FEED	
30	VIDEO BIAS FEED	



Part Number System



Parameter	Value	Units	
Upper Frequency ¹	2.2	GHz	
Power Output	300	W	
Package	Plastic Overmold	-	

Table 1.

Note¹: Alpha characters used in frequency code indicate a value greater than 9.9 GHz. See Table 2 for value.

Character Code	Code Value
А	0
В	1
С	2
D	3
E	4
F	5
G	6
Н	7
J	8
K	9
Examples:	1A = 10.0 GHz 2H = 27.0 GHz

Table 2.



Disclaimer

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